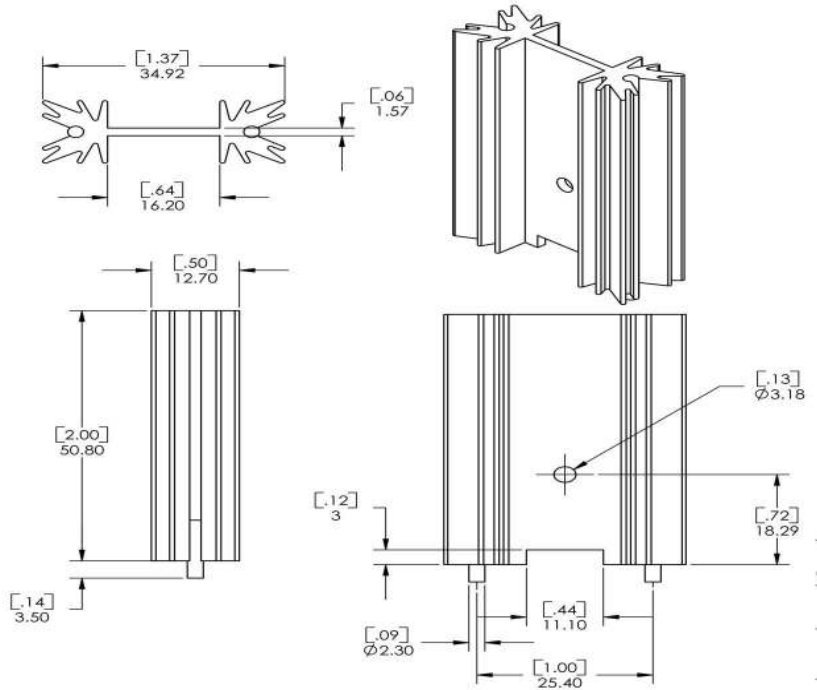
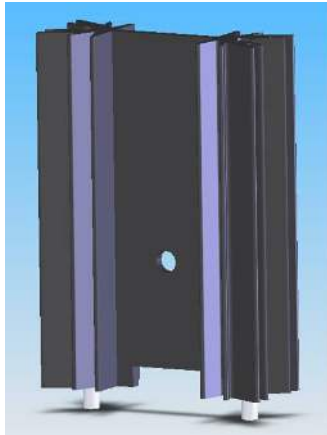


# Board Level Heat Sinks



ThermaFlo

P/N: 411320B02500



## PRODUCT SPECIFICATIONS

- Devices: TO-218, TO-220 & TO-247
- Size: 12.7 x 34.9 x 50.8 mm
- Material: Aluminum
- Weight: 20.9 g
- Type: Stamped
- Finish: Black Anodized
- PCB Mounting: Solderable Pins
- Package: Bulk
- Accessories: Hardware & Thermal Interface Material

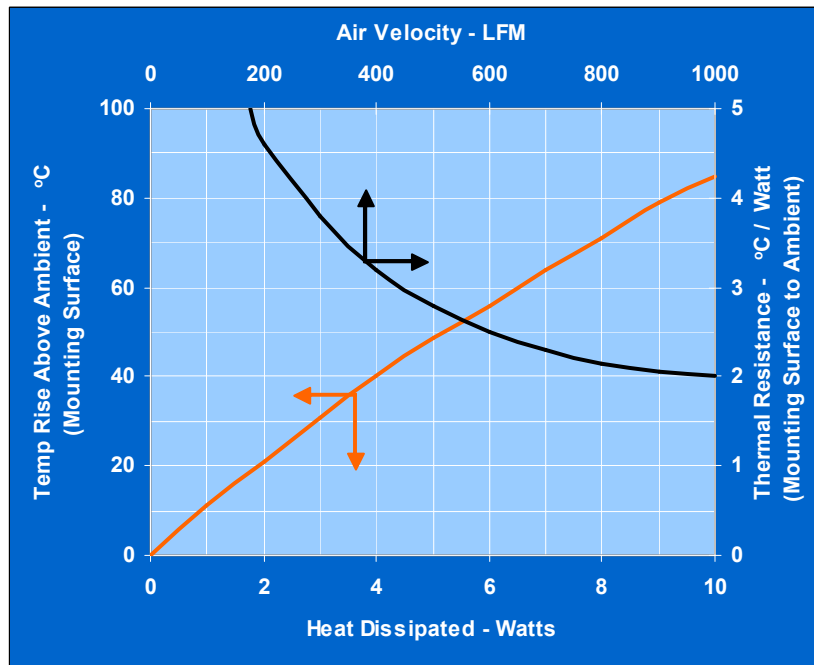
## FEATURES & BENEFITS

- Hole for Device Attachment
- Dual Device Cooling Heat Sink
- Vertical Mounting via Solderable Pins
- RoHS Compliant



## CUSTOMIZED HEATSINKS

- Specialized Plating
- Specialized Body Configurations
- Contact Applications Engineering



TO-218, TO-220 & TO-247

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